HOSTAFORM® SXT90Z-02 XAP®

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Hostaform® acetal copolymer grade SXT90Z-02 XAP® is a UV stabilized, impact modified material available in a range of colors for automotive interior applications, while also meeting the typical low emission requirements of the automotive market. Chemical abbreviation according to ISO 1043-1: POM-HI Low emission performance (VDA 275) < 10 ppm

Product information

Resin Identification	(POM+TPU)	ISO 1043
Part Marking Code	>(POM+TPU)<	ISO 11469

Rheological properties

Melt volume-flow rate	4	cm^3/10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	

Typical mechanical properties

Tensile modulus	1500	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	41	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	13	%	ISO 527-1/-2
Flexural modulus	1450	MPa	ISO 178
Flexural stress at 3.5%	40	MPa	ISO 178
Charpy impact strength, 23°C	N	kJ/m^2	ISO 179/1eU
Charpy impact strength, -30°C	N	kJ/m^2	ISO 179/1eU
Charpy notched impact strength, 23°C	13	kJ/m^2	ISO 179/1eA
Charpy notched impact strength, -30°C	8	kJ/m^2	ISO 179/1eA
Poisson's ratio	0.43[C]		

[C]: Calculated

Thermal properties

Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	65	°C	ISO 75-1/-2

Physical/Other properties

Water absorption, 2mm	0.65	%	Sim. to ISO 62
Density	1360	kg/m^3	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	190	°C
Min. melt temperature	180	°C
Max. melt temperature	200	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	65	°C
Min. mould temperature	60	°C
Max. mould temperature	70	°C
Hold pressure range	60 - 120	MPa

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Back pressure	2 MPa

Characteristics

Processing	Injection Moulding
Special characteristics	High impact or impact modified, U.V. stabilised or stable to weather, Low emissions

Additional information

Processing Notes

Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying to prevent splay and odor problems.

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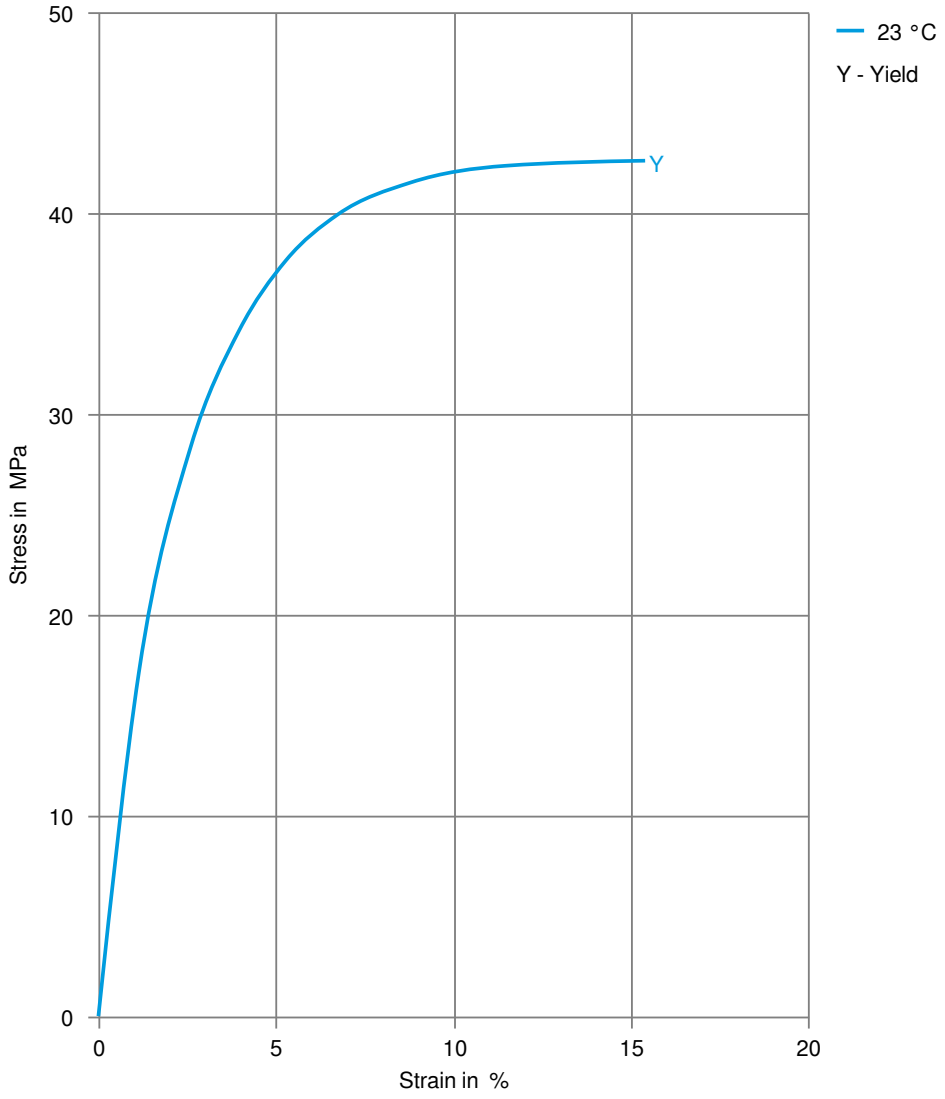
Stress-strain



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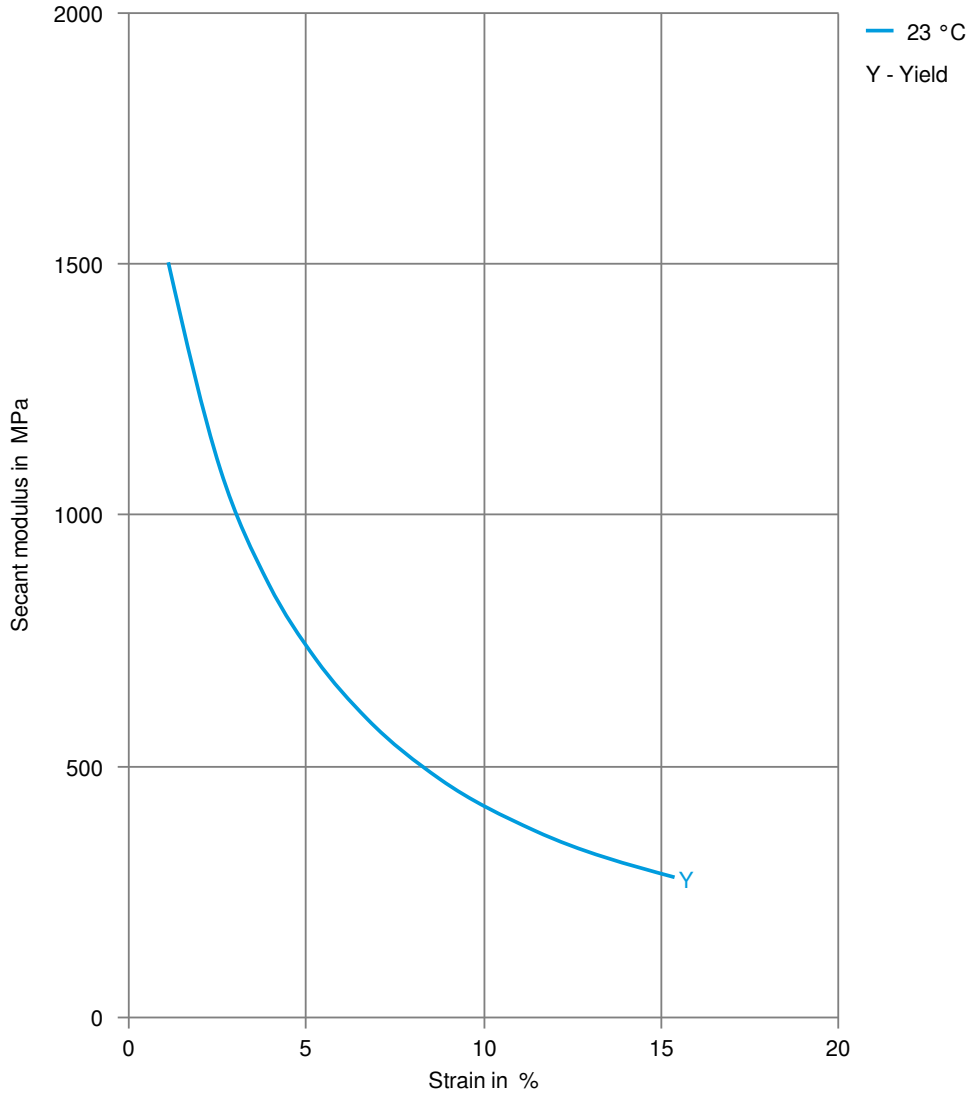
Secant modulus-strain



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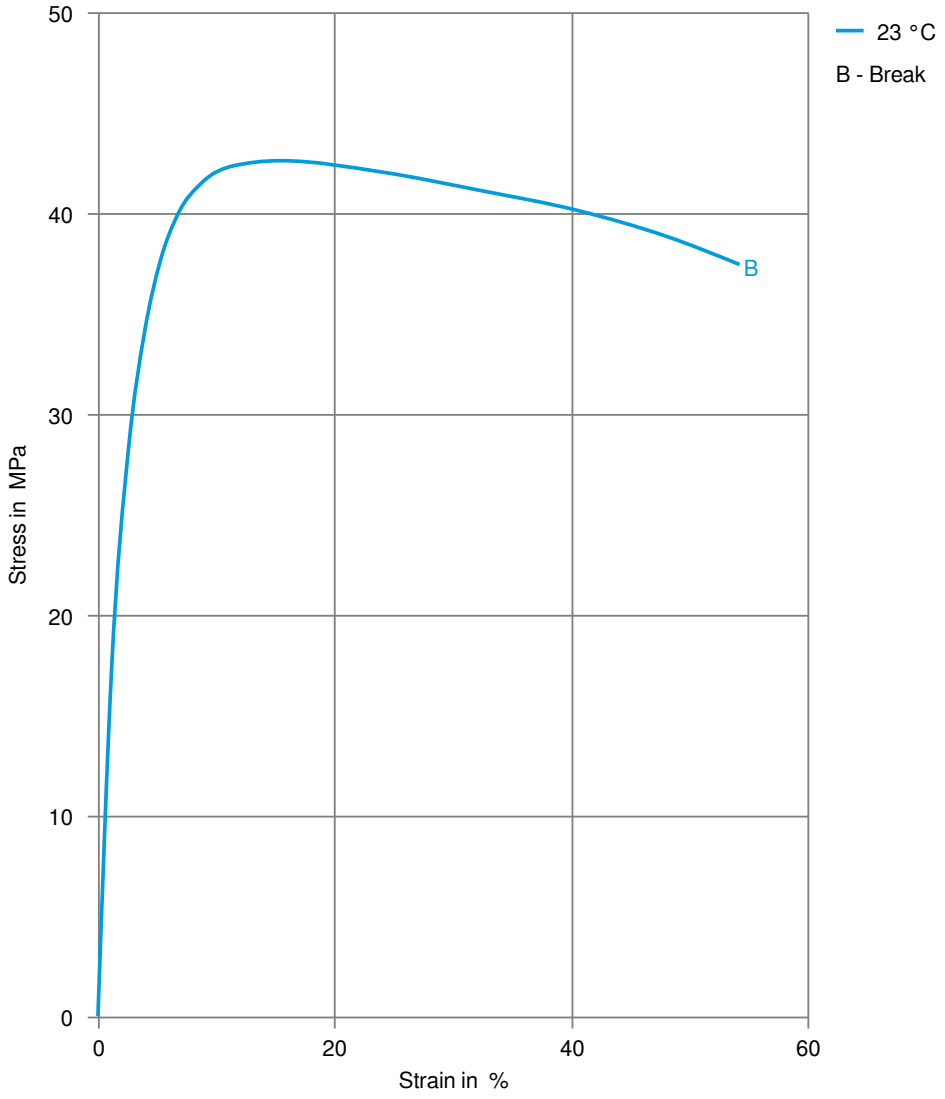
Stress-strain, 50mm/min



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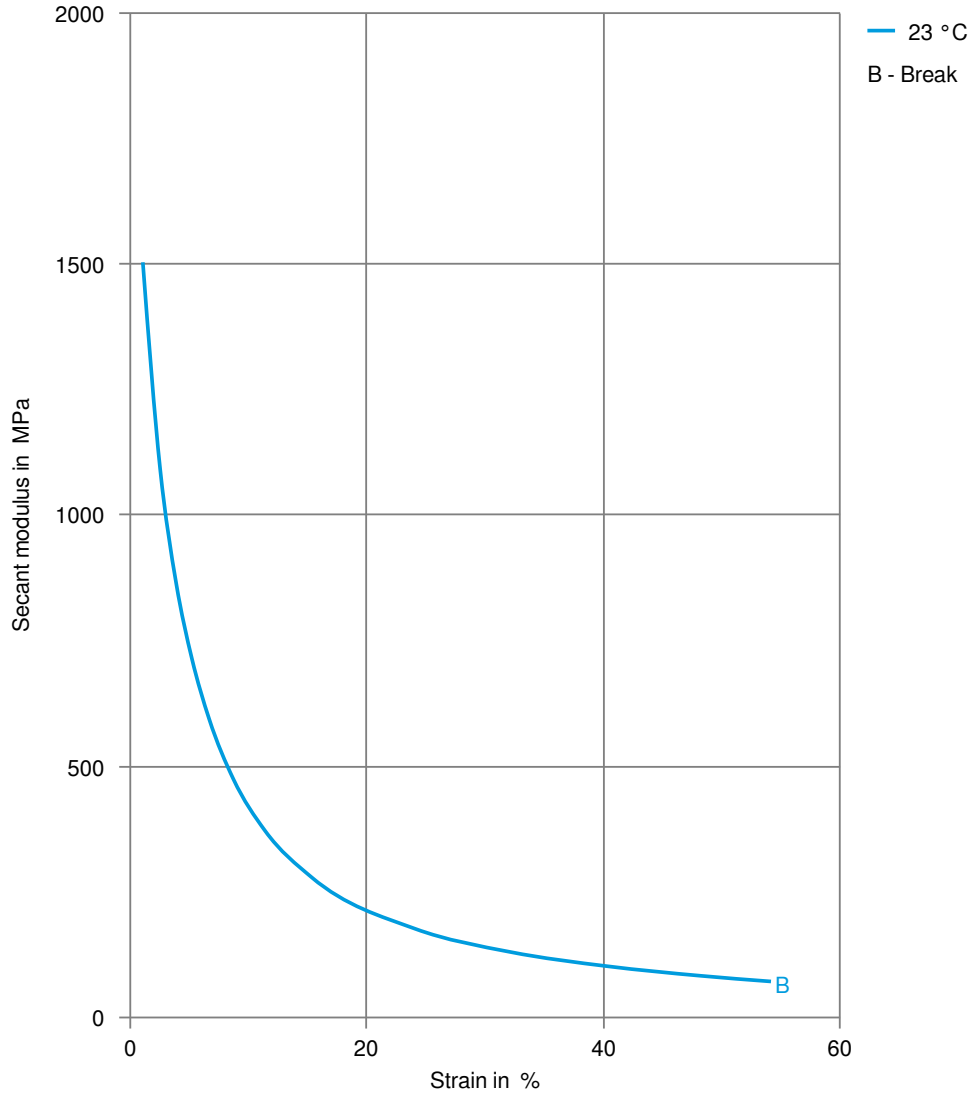
Secant modulus-strain, 50mm/min



Revised: 2024-12-03 Source: Celanese Materials Database